



Material Content Data Sheet



Sales Product Name		TLE4961-3K		Issued		19. July 2018			
MA#		MA000935468							
Package		PG-SC59-3-5		Weight*		13.84 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.350	2.52	2.52	25249	25249	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		76		
		non noble metal	titanium	7440-32-6	0.005	0.04		380	
		non noble metal	chromium	7440-47-3	0.016	0.11		1139	
		non noble metal	copper	7440-50-8	5.236	37.82	37.98	378229	379824
wire	noble metal	gold	7440-57-5	0.028	0.20	0.20	2000	2000	
encapsulation	organic material	carbon black	1333-86-4	0.077	0.55		5537		
		plastics	epoxy resin	-	1.648	11.90		119042	
		inorganic material	silicondioxide	60676-86-0	5.940	42.93	55.38	429107	553686
leadfinish	non noble metal	tin	7440-31-5	0.255	1.84	1.84	18439	18439	
plating	noble metal	silver	7440-22-4	0.158	1.14	1.14	11380	11380	
glue	plastics	epoxy resin	-	0.023	0.16		1649		
		noble metal	silver	7440-22-4	0.108	0.78	0.94	7773	9422
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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